## **MA2SD19**

### Silicon epitaxial planar type

For super high speed switching

#### ■ Features

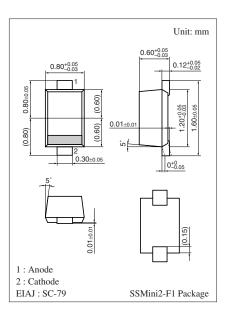
• Forward current (Average)  $I_{F(AV)} = 200 \text{ mA}$  rectification is possible

• Low forward voltage:  $V_F < 0.47 \text{ V}$ • Small reverse current:  $I_R < 20 \ \mu\text{A}$ 

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	20	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	20	V
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Peak forward current	$I_{FM}$	300	mA
Forward current (Average)	$I_{F(AV)}$	200	mA
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note)  $\ast$ : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



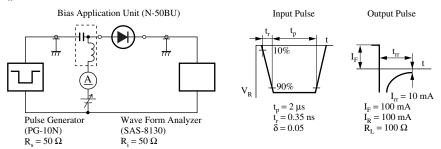
Marking Symbol: 3L

#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

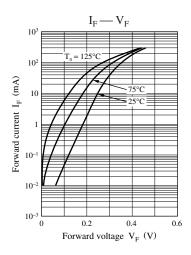
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F}$	$I_F = 200 \text{ mA}$			0.47	V
Reverse current	$I_R$	$V_R = 10 \text{ V}$			15	μA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		15		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		2		ns
		$I_{rr}=10 \text{ mA}, R_{L}=100 \Omega$				

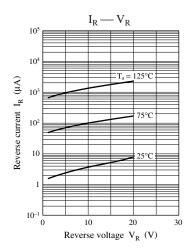
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

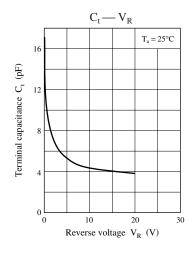
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.
- 4. \*: t<sub>rr</sub> measurement circuit



## **Panasonic**







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